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[52049-101LF](#)

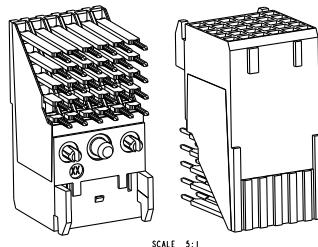
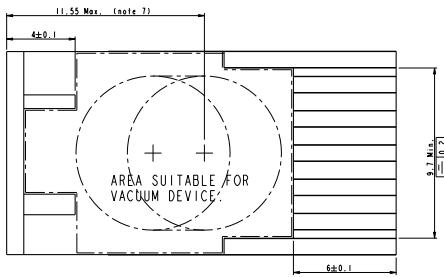
For any questions, you can email us directly:

sales@integrated-circuit.com

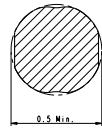
PRODUCT NUMBER	ROW	CONFIGURATION					
		6	5	4	3	2	1
52049-X01 (LF)	E	X	X	X	X	X	X
Performance	D	X	X	X	X	X	X
Temperature	C	X	X	X	X	X	X
Humidity	B	X	X	X	X	X	X
Altitude	A	X	X	X	X	X	X
Lead Free Designation							

--- POSITION NOT LOADED
-x- POSITION LOADED

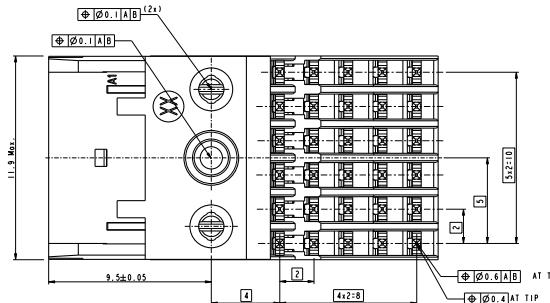
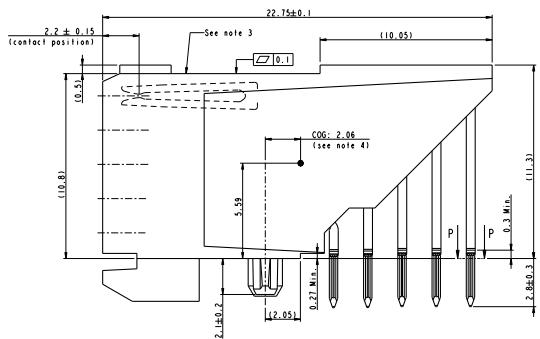
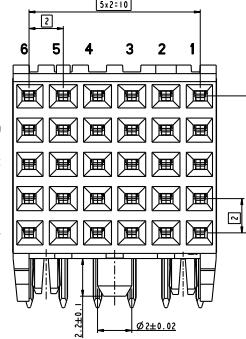
PRODUCT NUMBER	MATING PERFORMANCE LEVEL
52048-101LF	STANDARD P/N - TELCORDIA CO Compatible
52048-301(LF)	CUSTOMER SPECIFIC
52048-E01(LF)	CUSTOMER SPECIFIC



SCALE 5:



SECTION P-F
SCALE 100:1



NOTES

1. Housing material: Liquid Crystal Polymer 303 gloss.
2. All seal surfaces are made of UL 94-V0 Contact material phosphor bronze.
3. Product marking on indicated surface: part number and manufacturing code. It will not prevent picking up with a vacuum device.
4. Center of gravity = indicated point. Mass of product 0.57 g.
5. Maximum force of connector: 1.5 N.
6. This dimension shows maximum position of the centre of the vacuum nozzle. Recommended position is 9.5 mm in line with the pegs.
7. The connector is tape-and-seal packed according to GS-14-626, with a maximum tape length 44 mm and tape pitch 20 mm. The long hole recesses at the top allow use of gripper.
8. Product specification according to GS-12-218.
9. For pin-in-paste recommendations see sheet 2 and application guide GS-20-024.

NOTE: LEAD-FREE AND RoHS INFORMATION

PDM: Rev:G

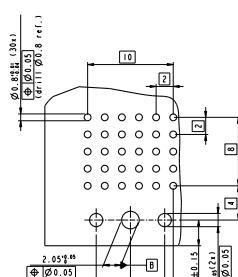
STATUS: **Released**

Printed: Sep 28, 2009

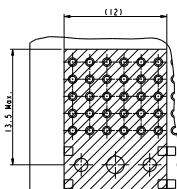
All items mentioned on this sheet are recommendations of FCI and should be seen as indication. The final responsibility for the application process is at the customer.

PCB LAYOUT: HOLE PATTERN

PCB thickness 1.4 - 2.6 mm

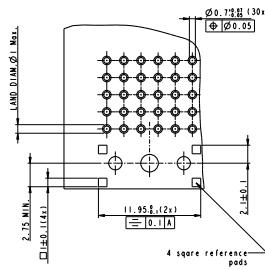


PCB LAYOUT: BOARD AREA



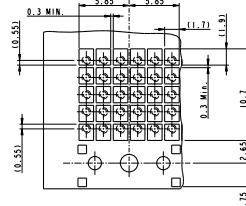
PCB LAYOUT: PLATING

Plating thickness must be constant over the connector area. Copper layer 50 μm max. Solder mask should cover all surfaces under the paste that are not plated. There is no solder mask allowed on the reference pads.



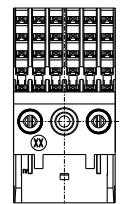
PCB LAYOUT : SOLDER PASTE

Recommended stencil thickness 0.15 mm.
The solder content in the paste should be sufficient, typically 50% volume percentage.
The solder foil, PCB, stencil and application process determine the solder result. The squeegee process (angle speed, pressure, material and number of cycles) must be optimized, so that sufficient solder is available.



CONNECTOR MOUNTING

The connector can be picked up with a mechanical gripper or a vacuum nozzle. Nozzle diameter 6 - 10 mm. Both metal nozzles or nozzles with seal or rubber can be used. Vacuum pressure 0.6 bar under local ambient pressure. Position of the nozzle on the connector as mentioned on sheet 1. The reference for placing the connector can be determined by video inspection of the connector bottomside. The recesses of the retention pegs are designed for video recognition (shown bold; see sketch below): The line through the center of the recesses is the reference for Y-direction and rotation; datum **[8]**. The line through the middle below the center of the recesses is the reference for X-direction and height differences for Y-direction.



The acceleration and the deceleration of the mounting head of the pick and place equipment should be restricted in such a way that the connector doesn't fall off or slides on the nozzle. An inferior accuracy of the placing equipment can reduce the success rate of mounting.

The last movement of the connector must be purely vertical and downwards. The board must be horizontal. The final mounting force must be controlled in such a way that the connector is sealed flush to the board and remains there after releasing from the placing device. (Extra PCB support can be required to meet this. The movement of the PCB assembly before reflowing must be smooth

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